

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**Applicants** 

: Makoto FUKUDA et al.

Group Art Unit: Not Yet Assigned

Appl. No.

: 10/553,950

(U.S. National Stage of PCT/JP2004/005870)

I.A. Filed

: April 23, 2004

Examiner: Not Yet Assigned

For

: HOLLOW FIBER MEMBRANE TYPE FLUID TREATMENT

**DEVICE** 

## INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
U.S. Patent and Trademark Office
Customer Service Window, Mail Stop AMENDMENT
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Sir:

In accordance with the duty of disclosure under 37 C.F.R. § 1.56 and §§1.97-1.98, Applicants hereby bring the following information to the attention of the Examiner in charge of the above-identified application, which includes information cited and discussed in the specification and the International Search Report issued in connection with International Patent Application No.

PCT/JP2004/005870, of which the present application is the U.S. National Stage Application. A copy of the International Search Report was enclosed with the papers when entering the U.S. National Stage on October 21, 2005. The Examiner is invited to review these materials to inspect the relevance indicated during international examination with respect to the documents cited therein.

The following is a list of the documents cited in the above-noted documents:

Japanese Patent No. 3080430, together with an English language abstract of patent family member Japanese Laid-open Patent Publication No. HEI 4-227030. Applicants note that the Japanese patent is cited and discussed on page 3 of the specification of the present application;

Japanese Patent Publication after Notice of Acceptance No. SHO 5918084, together with an English language abstract of patent family member
Japanese Laid-open Patent Publication No. SHO 53-35683. Applicants note that
the Japanese patent publication No. SHO 59-18084 is cited and discussed on
page 3 of the specification of the present application;

Japanese Laid-open Patent Publication No. HEI 8-246283, together with an English language abstract and translation of the same. Applicants note that this document is cited and discussed on page 3 of the specification of the present application;

Japanese Laid-open Patent Publication No. SHO 57-194007, together with an English language abstract of the same. Applicants note that this document is cited and discussed on page 3 of the specification of the present application;

International Patent Publication No. WO 01/60477. Applicants note that this document is cited and discussed on page 3 of the specification of the present application;

Japanese Laid-open Patent Publication No. HEI 8-173527, together with an English language abstract of the same. Applicants note that this document is cited and discussed on page 3 of the specification of the present application;

Japanese Patent No. 3151168, together with an English language abstract of patent family member Japanese Laid-open Patent Publication No. HEI 10-305218. Applicants note that the Japanese patent is cited and discussed on pages 4 and 5 of the specification of the present application;

Japanese Laid-open Patent Publication No. SHO 59-4403, together with an English language abstract of the same. Applicants note that this document is cited and discussed on pages 4 and 5 of the specification of the present application;

Japanese Laid-open Patent Publication No. 2000-42100, together with an English language abstract of the same. Applicants note that this document is cited and discussed on page 5 of the specification of the present application;

Japanese Laid-open Patent Publication No. 2000-350781, together with an English language abstract of the same. Applicants note that this document is cited and discussed on page 6 of the specification of the present application;

Japanese Laid-open Patent Publication No. 2003-102833, together with an English language abstract and translation of the same. Applicants note that this document is cited and discussed on pages 6 and 7 of the specification of the present application;

Japanese Laid-open Patent Publication No. SHO 53-31828;

Japanese Laid-open Patent Publication No. 2003-111836, together with an English language abstract of the same and patent family member U.S. Patent Application Publication No. 2003/0028073; and

Japanese Laid-open Patent Publication No. SHO 44-5526.

P28510.A02.Doc

Further to 37 C.F.R. §1.98 (a)(2)(ii), a copy of the U.S. patent application publication is not enclosed herewith. However, if a copy is needed, the Examiner is respectfully requested to contact the undersigned.

Applicants respectfully request that the Examiner consider the above material and cite the same. Copies of the above-noted foreign documents are attached hereto and all of the above-noted documents are listed on the attached PTO-1449 Form. The Examiner is requested to initial the appropriate spaces on the attached Form and to return a copy of the completed Form to Applicants with the next official communication in the present application.

Applicants note that an Office Action on the merits has not issued in the present application, and thus no fee is believed necessary to ensure consideration of the submitted material. However, if an Office Action on the merits has issued and is crossing this statement in the mail, the undersigned authorizes the Commissioner to charge any fee necessary for the consideration of this statement, including any payment under 37 C.F.R. §1.17 (p) to Deposit Account No. 19-0089.

P28510.A02.Doc

Should the Examiner have any questions, the Examiner is invited to contact the undersigned at the below-listed telephone number.

Respectfully Submitted, Makoto FUKUDA et al.

Bruce H. Bernstein

Reg. No. 29,027

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February 9, 2006 GREENBLUM & BERNSTEIN, P.L.C. 1950 Roland Clarke Place Reston, VA 20191 (703) 716-1191 FORM PTO-1449

S. Department of Commerce Patent and Trademark Office Atty. Docket P28510

Filing Date

April 23, 2004

Application No 10/553,950

INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)

Applicant Makoto FUKUDA et al.

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U.S. PATENT DOCUMENTS												

EXAMINER INITIAL														
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	2003	0	0	2	8	0	7	3	02/02/03	MOCHIZUKI et al.				
									FOREIGN PAT	ENT DOCUMENTS				
	-	DOCUMENT NUMBER					BER		DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO	
		3	0	8	0	4	3	0	06/23/00	JAPAN				
	59	-		1	8	0	8	4	04/25/84	JAPAN	-			
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	2	An English language abstract of patent family member Japanese Laid-open Patent Publication No. SHO 53-35683.												
	3	English language Abstract of JP 57-194007.												
	4	English language Abstract of JP 8-246283.												
	5	English language Abstract of JP 8173527.												
	6	English language Abstract of JP 10-305218.												
	7	English language Abstract of JP 59-4403.												
	8	English language Abstract of JP 2000-42100.												
	9	English language Abstract of JP 2000-350781.												
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**EXAMINER** 

DATE CONSIDERED

\*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.